MYD-Y7Z010/20 Development Board

- ➤ MYC-Y7Z010/20 CPU Module as Controller Board
- ➤ 1.27mm pitch 180-pin Stamp Hole Expansion Interface for Board-to-Board Connections
- ► 667MHz Xilinx XC7Z010 or XC7Z020 ARM Cortex-A9 Processor with Xilinx 7-series FPGA logic
- > 512MB DDR3 SDRAM (2 x 256MB, 32-bit)
- > 4GB eMMC Flash, 16MB QSPI Flash
- ▶ USB Host, 3 x Gigabit Ethernet ports, RS232, RS485, CAN, TF, JTAG, GPIO...
- > Optional 4.3- or 7-inch LCD Module, WiFi Module, Camera Module and IO Extension Cape
- Ready-to-Run Linux 3.15.0



Figure 1-1 MYD-Y7Z010/20 Development Board

Description

The MYD-Y7Z010/20 development board is powered by Xilinx XC7Z020 (Zynq-7020) or XC7Z010 (Zynq-7010) SoC device. It is a cost-effective and high-performance solution for industrial application such as Industrial Ethernet, machine vision, PLC/HMI and etc. The board is ready to run Linux and supports industrial operating temperature ranging from -40 to +85 Celsius.

The MYD-Y7Z010/20 development board employs the MYC-Y7Z010/20 as the controller board by populating the CPU Module on its base board through 1.27mm pitch 180-pin stamp-hole (Castellated-Hole) interface, allowing users to take the advantages of numerous extended out signals. Core components on CPU Module including Z-7010 or Z-7020 processor, 512MB DDR3 SDRAM, 4GB eMMC, 16MB QSPI Flash, Gigabit Ethernet PHY and external watchdog. Additionally, the MYD-Y7Z010/20 development board takes full features of the Z-7010 or Z-7020 all programmable SoC to create a rich set of peripherals to the base board through headers and connectors including RS232, RS485, USB Host, three Gigabit Ethernet ports, CAN, TF card slot, JTAG as well as one 2.54mm pitch 2 x 25-pin expansion header to let more GPIOs available for further extension.

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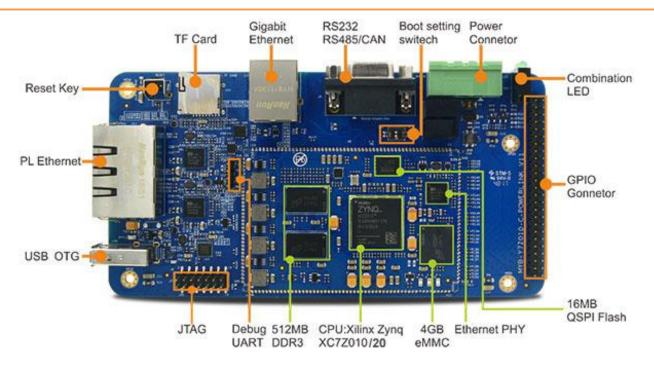


Figure 1-2 MYD-Y7Z010/20 Development Board

MYIR has designed an IO expansion board <u>MYD-Y7Z010/20 IO Cape</u> to connect to the <u>MYD-Y7Z010/20</u> <u>development board</u> via the 2.54mm pitch 2 x 25-pin expansion header to expand and enhances its functionality with added peripherals and signals including HDMI, Camera, LCD and Pmods.

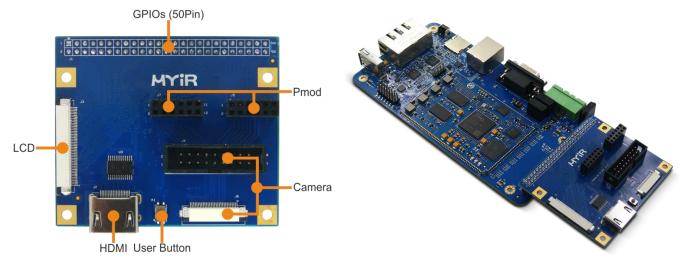


Figure 1-3 MYD-Y7Z010/20 IO Cape

Figure 1-4 IO Cape Mounted on Development Board

The 4.3- and 7-inch LCD Modules as well as MY-CAM011B camera module from MYIR can be supported through the MYD-Y7Z010/20 IO Cape. Optional USB Camera modules is also provided. With all these features, the MYD-Y7Z010/20 board is not only great for integration into custom design, but also can be used as a stand-alone development board for evaluating solutions based on Xilinx Zynq-7000.

Hardware Specification

The Zynq®-7000 All Programmable SoC (AP SoC) family integrates the software programmability of an ARM®-based processor with the hardware programmability of an FPGA, enabling key analytics and hardware acceleration while integrating CPU, DSP, ASSP, and mixed signal functionality on a single device. Consisting of single-core Zynq-7000S and dual-core Zynq-7000 devices, the Zynq-7000 family is the best price to performance per-watt, fully scalable SoC platform for your unique application requirements.

Zynq-7000S

Zynq-7000S devices feature a single-core ARM Cortex[™]-A9 processor mated with 28nm Artix®-7 based programmable logic, representing the lowest cost entry point to the scalable Zynq-7000 platform. It includes Zynq Z-7007S, Z-7012S and Z-7014S which target smaller embedded designs. Available with 6.25Gb/s transceivers and outfitted with commonly used hardened peripherals, the Zynq-7000S delivers cost-optimized system integration ideal for industrial IoT applications such as motor control and embedded vision.

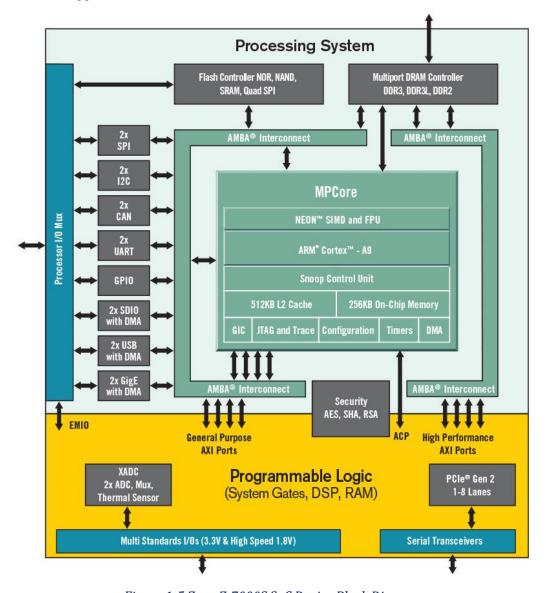


Figure 1-5 Zynq Z-7000S SoC Device Block Diagram

Zynq-7000

Zynq-7000 devices are equipped with dual-core ARM Cortex-A9 processors integrated with 28nm Artix-7 or Kintex®-7 based programmable logic for excellent performance-per-watt and maximum design flexibility. With up to 6.6M logic cells and offered with transceivers ranging from 6.25Gb/s to 12.5Gb/s, Zynq-7000 devices enable highly differentiated designs for a wide range of embedded applications including multi-camera drivers assistance systems and 4K2K Ultra-HDTV.

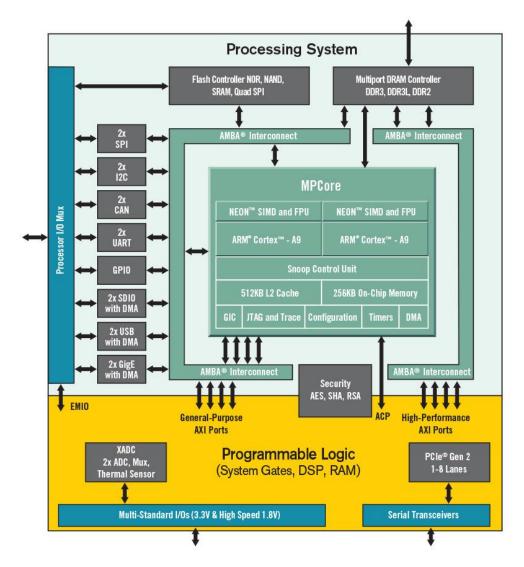


Figure 1-6 Zynq Z-7000 SoC Device Block Diagram

Zynq®-7000 All Programmable SoC Family

	Cost-Optimized Devices					Mid-Range Devices				
Device Name	Z-7007S	Z-7012S	Z-7014S	Z-7010	Z-7015	Z-7020	Z-7030	Z-7035	Z-7045	Z-7100
Part Numbe	XC7Z007S	XC7Z012S	XC7Z014S	XC7Z010	XC7Z015	XC7Z020	XC7Z030	XC7Z035	XC7Z045	XC7Z100
Processor Core	Single-Core ARM® Cortex™-A9 MPCore™ Up to 766MHz			Dual-Core ARM Cortex-A9 MPCore Up to 866MHz		Dual-Core ARM Cortex-A9 MPCore Up to 1GHz ⁽¹⁾				
Processor Extension		NEON™ SIMD Engine and Single/Double Precision Floating Point Unit per processor								
L1 Cache	32KB Instruction, 32KB Data per processor									
L2 Cache		512KB								
On-Chip Memor		256KB								
External Memory Support ⁽²		DDR3, DDR3L, DDR2, LPDDR2								
External Static Memory Support(2		2x Quad-SPI, NAND, NOR								
DMA Channel	8 (4 dedicated to PL)									
Peripheral:		2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO								
Peripherals w/ built-in DMA ⁽²⁾		2x USB 2.0 (OTG), 2x Tri-mode Gigabit Ethernet, 2x SD/SDIO								
Security ⁽³	RSA Authentication of First Stage Boot Loader, AES and SHA 256b Decryption and Authentication for Secure Boot									
Processing System to Programmable Logic Interface Port: (Primary Interfaces & Interrupts Only	4x AXI 64b/32b Memory									
7 Series PL Equivalen	Artix®-7	Artix-7	Artix-7	Artix-7	Artix-7	Artix-7	Kintex®-7	Kintex-7	Kintex-7	Kintex-7
Logic Cell:	23K	55K	65K	28K	74K	85K	125K	275K	350K	444K
Look-Up Tables (LUTs	14,400	34,400	40,600	17,600	46,200	53,200	78,600	171,900	218,600	277,400
					40,200	33,200				2/1,400
Flip-Flop		68,800	81,200	35,200	92,400	106,400	157,200	343,800	437,200	554,800
Flip-Flop: Total Block RAN	28,800	68,800 2.5Mb	81,200 3.8Mb	LLUCKBOOK STATISTICS	The second secon		The second secon	The second secon	The second secon	- Committee of the Comm
100000000000000000000000000000000000000	28,800 1.8Mb	The state of the s	-	35,200	92,400	106,400	157,200	343,800	437,200	554,800
Total Block RAM	28,800 1.8Mb (50)	2.5Mb	3.8Mb	35,200 2.1Mb	92,400 3.3Mb	106,400 4.9Mb	157,200 9.3Mb	343,800 17.6Mb	437,200 19.2Mb	554,800 26.5Mb
Total Block RAN (# 36Kb Blocks	28,800 1.8Mb (50) 66	2.5Mb (72)	3.8Mb (107)	35,200 2.1Mb (60)	92,400 3.3Mb (95)	106,400 4.9Mb (140)	157,200 9.3Mb (265)	343,800 17.6Mb (500)	437,200 19.2Mb (545)	554,800 26.5Mb (755)
Total Block RAN (# 36Kb Blocks DSP Slice PCI Express	28,800 1.8Mb (50) 66	2.5Mb (72) 120	3.8Mb (107)	35,200 2.1Mb (60) 80	92,400 3.3Mb (95) 160 Gen2 x4	106,400 4.9Mb (140) 220	157,200 9.3Mb (265) 400	343,800 17.6Mb (500) 900 Gen2 x8	437,200 19.2Mb (545) 900	554,800 26.5Mb (755) 2,020
Total Block RAN (# 36Kb Blocks DSP Slice:	28,800 1.8Mb (50) 66	2.5Mb (72) 120 Gen2 x4	3.8Mb (107) 170	35,200 2.1Mb (60) 80 — 2x 12 bit,	92,400 3.3Mb (95) 160 Gen2 x4 MSPS ADC	106,400 4.9Mb (140) 220 — s with up to	157,200 9.3Mb (265) 400 Gen2 x4 17 Differentia	343,800 17.6Mb (500) 900 Gen2 x8	437,200 19.2Mb (545) 900 Gen2 x8	554,800 26.5Mb (755) 2,020
Total Block RAM (# 36Kb Blocks DSP Slice: PCI Express ¹ Analog Mixed Signal (AMS) / XADC ¹²	28,800 1.8Mb (50) 66	2.5Mb (72) 120 Gen2 x4	3.8Mb (107) 170	35,200 2.1Mb (60) 80 — 2x 12 bit,	92,400 3.3Mb (95) 160 Gen2 x4 MSPS ADC	106,400 4.9Mb (140) 220 — s with up to	157,200 9.3Mb (265) 400 Gen2 x4 17 Differentia	343,800 17.6Mb (500) 900 Gen2 x8 al Inputs	437,200 19.2Mb (545) 900 Gen2 x8	554,800 26.5Mb (755) 2,020
Total Block RAM (# 36Kb Blocks DSP Slice: PCI Express Analog Mixed Signal (AMS) / XADC ⁽² Security ⁽³	28,800 1.8Mb (50) 66	2.5Mb (72) 120 Gen2 x4	3.8Mb (107) 170	35,200 2.1Mb (60) 80 — 2x 12 bit,	92,400 3.3Mb (95) 160 Gen2 x4 MSPS ADC: tion & Author	106,400 4.9Mb (140) 220 — s with up to	157,200 9.3Mb (265) 400 Gen2 x4 17 Differentia	343,800 17.6Mb (500) 900 Gen2 x8 al Inputs grammable Log	437,200 19.2Mb (545) 900 Gen2 x8	554,800 26.5Mb (755) 2,020 Gen2 x8

Figure 1-7 Zynq-7000 SoC Device Table

Mechanical Parameters

Dimensions: 153mm x 80mm (base board), 75mm x 50mm (CPU Module)

PCB Layers: 4-layer design (base board), 10-layer design (CPU Module)

Power supply: 12V/2A

Working temp.: -40~85 Celsius

The MYD-Y7Z010/20 Controller Board (MYC-Y7Z010/20 CPU Module)

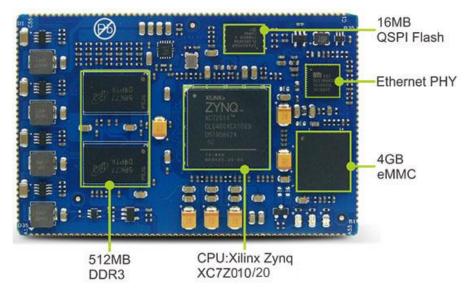


Figure 1-8 MYC-Y7Z010/20 CPU Module

¹ GHz processor frequency is available only for -3 speed grades in Z-7035, Z-7035, and Z-7045 devices. See <u>DS190</u>, Zynq-7000 All Programmable SoC Overview for details. Z-7007S and Z-7010 in CLG225 have restrictions on PS peripherals, memory interfaces, and I/Os. Please refer to <u>UGS35</u>, Zynq-7000 All Programmable SoC Technical Refer Security block is shared by the Processing System and the Programmable Logic.

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SoC

- ✓ Xilinx XC7Z010-1CLG400I (Zynq-7010) or XC7Z020-1CLG400I (Zynq-7020)
 - ARM® Cortex[™]-A9 MPCore processor
 - 667MHz dual-core processor (up to 866MHz, for XC7Z010 or XC7Z020)
 - Integrated Artix-7 class FPGA subsystem
 - with 85K logic cells, 53,200 LUTs, 220DSP slices (for XC7Z020)
 - with 23K logic cells, 14,400 LUTs, 66DSP slices (for XC7Z007S)
 - NEON™ & Single / Double Precision Floating Point for each processor
 - Supports a Variety of Static and Dynamic Memory Interfaces

Memory

- ✓ 512MB DDR3 SDRAM
- ✓ 4GB eMMC Flash
- ✓ 16MB QSPI Flash

Peripherals and Signals Routed to Pins



- ✓ Gigabit Ethernet PHY
- ✓ External watchdog
- ✓ Three LEDs
 - One red LED for power indicator
 - One green LED for FPGA program done indicator
 - One flashing green LED for system indicator
- ✓ 1.27mm 180-pin expansion connectors bring out below signals:
 - One Gigabit Ethernet
 - One USB OTG2.0 (need external USB PHY-USB3320)
 - Two Serial ports
 - Two I2C
 - Two CAN BUS
 - Two SPI
 - * Serial ports, I2C, CAN and SPI signals can be implemented through PL pins by Emio
 - Two ADC (two independent differential ADC, 16-channel ADC brought out through PL pins)
 - One SDIO

The MYD-Y7Z010/20 Base Board

PS Unit

- ✓ One USB Host
- ✓ One RS232 serial port (with isolation)
- ✓ One RS485 (with isolation)
- ✓ One TF card slot
- ✓ One CAN interface (with isolation)
- ✓ One 10/100/1000Mbps Ethernet interface
- ✓ One 2.54mm pitch 14-pin JTAG interface
- ✓ One Debug serial port (UART)

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PL Unit

- ✓ One 2.54mm pitch 2 x 25-pin GPIO expansion headers
- ✓ Two 10/100/1000Mbps Ethernet interfaces
- ✓ Three user LEDs

Function Block Diagram

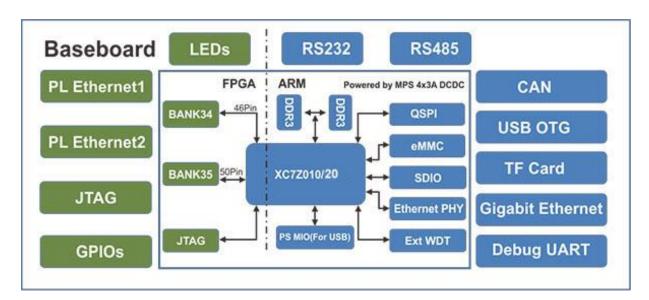


Figure 1-9 Function Block Diagram of MYD-Y7Z010/20

Dimension Chart

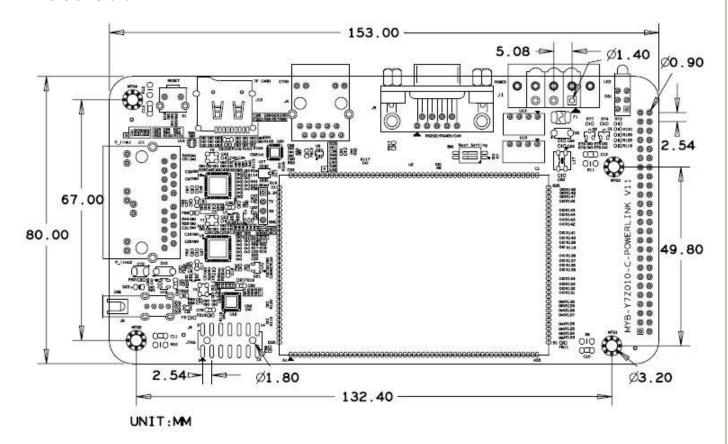


Figure 1-10 Dimension Chart of MYD-Y7Z010/20



Software Features

Item	Features	Description	Remark
Cross compiler	gcc 4.6.1	gcc version 4.6.1 (SourceryCodeBench Lite 2011.09-50)	
Boot program	BOOT.BIN	First boot program including FSBL, bitstream	Source code provided
	u-boot	Secondary boot program	Source code provided
Linux Kernel	Linux 3.15.0	Customized kernel for MYD-Y7Z010/20 Development Board	Source code provided
Drivers	USB Host	USB Host driver	Source code provided
	Ethernet	Gigabit Ethernet driver	Source code provided
	MMC/SD/TF	MMC/SD/TF card driver	Source code provided
	CAN	CAN driver	Source code provided
	LCD Controller	LCD driver	Source code provided
	HDMI	HDMI (SII902X chip) driver	Source code provided
	Button	Button driver	Source code provided
	UART	UART driver	Source code provided
	LED	LED driver	Source code provided
	GPIO	GPIO driver	Source code provided
	QSPI	QSPI Flash W25Q128FW driver	Source code provided
	RTC	DS3231 RTC driver	Source code provided
	Resistive Touch	TSC2007 resistive touch screen driver	Source code provided
	Capacitive Touch	FT5X0X capacitive touch screen driver	Source code provided
	ADC	ADC driver	Source code provided
File System	Ramdisk	Ramdisk system image	
	Rootfs.tar	Tar file	

Table 1-1 Software Features of MYD-Y7Z010/20